

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



### Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









### HMC583LP5 / 583LP5E

v03.1210



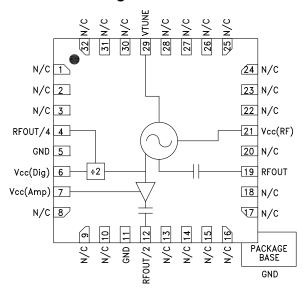
# MMIC VCO w/ HALF FREQUENCY OUTPUT & DIVIDE-BY-4, 11.5 - 12.8 GHz

### Typical Applications

Low noise MMIC VCO w/Half Frequency, Divide-by-4 Outputs for:

- Point to Point/Multipoint Radio
- Test Equipment & Industrial Controls
- SATCOM
- Military End-Use

### **Functional Diagram**



#### **Features**

Dual Output: Fo = 11.5 - 12.8 GHzFo/2 = 5.75 - 6.4 GHz

Pout: +11 dBm

Phase Noise: -110 dBc/Hz @100 kHz Typ.

No External Resonator Needed

32 Lead 5x5mm SMT Package: 25mm²

### General Description

The HMC583LP5 & HMC583LP5E are GaAs InGaP Heterojunction Bipolar Transistor (HBT) MMIC VCOs. The HMC583LP5 & HMC583LP5E integrate resonators, negative resistance devices, varactor diodes and feature half frequency and divide-by-4 outputs. The VCO's phase noise performance is excellent over temperature, shock, and process due to the oscillator's monolithic structure. Power output is +11 dBm typical from a +5V supply voltage. The prescaler and RF/2 functions can be disabled to conserve current if not required. The voltage controlled oscillator is packaged in a leadless QFN 5x5 mm surface mount package, and requires no external matching components.

### Electrical Specifications, $T_{\Delta} = +25^{\circ}$ C, Vcc (Dig), Vcc (Amp), Vcc (RF) = +5V

Parameter		Min.	Тур.	Max.	Units
Frequency Range	Fo Fo/2		11.5 - 12.8 5.75 - 6.4		GHz GHz
Power Output	RFOUT/2 RFOUT/4	+7 +9 -9		+13 +15 -3	dBm dBm dBm
SSB Phase Noise @ 100 kHz Offset, Vtune= +5V @ RFOUT			-110		dBc/Hz
Tune Voltage	Vtune	2		12	V
Supply Current	Icc(Dig) + Icc(Amp) + Icc(RF)	310	350	390	mA
Tune Port Leakage Current (Vtune= 12V)				10	μΑ
Output Return Loss			2		dB
Harmonics/Subharmonics	1/2 2nd 3rd		26 22 30		dBc dBc dBc
Pulling (into a 2.0:1 VSWR)			3		MHz pp
Pushing @ Vtune= 5V			20		MHz/V
Frequency Drift Rate			1.0		MHz/°C

### **HMC583\* PRODUCT PAGE QUICK LINKS**

Last Content Update: 02/23/2017

### COMPARABLE PARTS -

View a parametric search of comparable parts.

### **EVALUATION KITS**

• HMC583LP5 Evaluation Board.

### **DOCUMENTATION**

#### **Data Sheet**

• HMC583 Data Sheet

### REFERENCE MATERIALS 🖵

#### **Quality Documentation**

- Package/Assembly Qualification Test Report: 32L 5x5mm QFN Package (QTR: 10009 REV: 05)
- Package/Assembly Qualification Test Report: LP3, LP4, LP5 & LP5G (QTR: 2014-00145)
- Package/Assembly Qualification Test Report: Plastic Encapsulated QFN (QTR: 05006 REV: 02)
- Semiconductor Qualification Test Report: GaAs HBT-A (QTR: 2013-00228)

### **DESIGN RESOURCES**

- HMC583 Material Declaration
- PCN-PDN Information
- · Quality And Reliability
- Symbols and Footprints

### **DISCUSSIONS**

View all HMC583 EngineerZone Discussions.

### SAMPLE AND BUY 🖵

Visit the product page to see pricing options.

### **TECHNICAL SUPPORT**

Submit a technical question or find your regional support number.

### DOCUMENT FEEDBACK 🖳

Submit feedback for this data sheet.

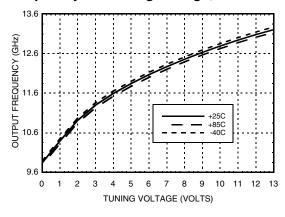


RoHS√

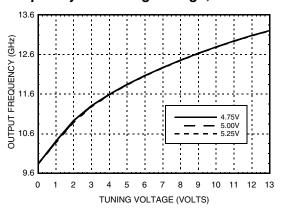
## MMIC VCO w/ HALF FREQUENCY OUTPUT & DIVIDE-BY-4, 11.5 - 12.8 GHz

### Frequency vs. Tuning Voltage, Vcc = +5V

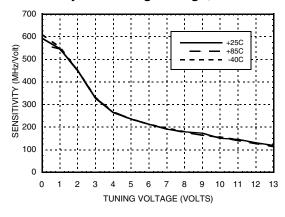
v03.1210



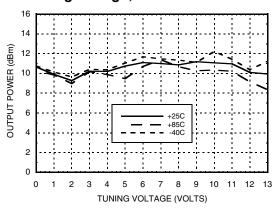
### Frequency vs. Tuning Voltage, T= 25°C



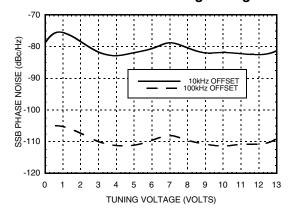
### Sensitivity vs. Tuning Voltage, Vcc = +5V



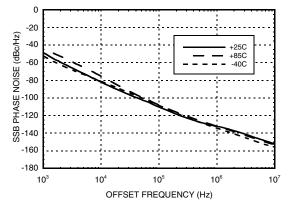
## Output Power vs. Tuning Voltage, Vcc = +5V



### SSB Phase Noise vs. Tuning Voltage



### SSB Phase Noise @ Vtune = +5V

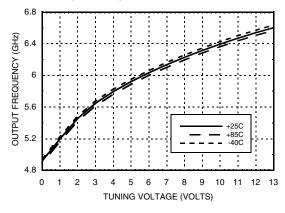






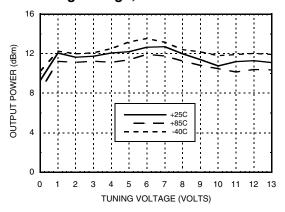
# MMIC VCO w/ HALF FREQUENCY OUTPUT & DIVIDE-BY-4, 11.5 - 12.8 GHz

## RFOUT/2 Frequency vs. Tuning Voltage, Vcc = +5V

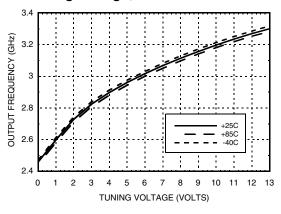


v03.1210

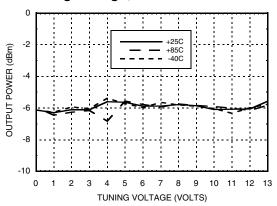
## RFOUT/2 Output Power vs. Tuning Voltage, Vcc = +5V



## Divide-by-4 Frequency vs. Tuning Voltage, Vcc = +5V



## Divide-by-4 Output Power vs. Tuning Voltage, Vcc = +5V



### **Absolute Maximum Ratings**

Vcc(Dig), Vcc(Amp), Vcc(RF)	+5.5 Vdc
Vtune	0 to +15V
Junction Temperature	135 °C
Continuous Pdiss (T=85 °C) (derate 43.5 mW/C above 85 °C	2.17 W
Thermal Resistance (junction to ground paddle)	23 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A

### Typical Supply Current vs. Vcc

Vcc (V)	Icc (mA)
4.75	320
5.00	350
5.25	380

Note: VCO will operate over full voltage range shown above.



ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

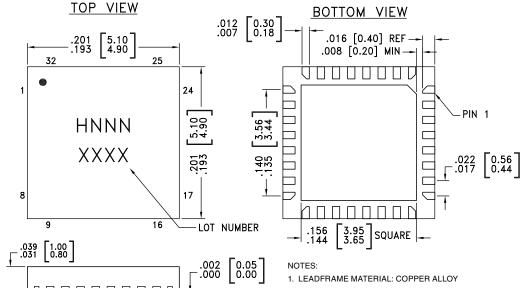


v03.1210



# MMIC VCO w/ HALF FREQUENCY OUTPUT & DIVIDE-BY-4, 11.5 - 12.8 GHz

### **Outline Drawing**



PLANE

- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM. PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

### Package Information

☐ .003[0.08] C

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC583LP5	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL3 <sup>[1]</sup>	H583 XXXX
HMC583LP5E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL3 [2]	<u>H583</u> XXXX

- [1] Max peak reflow temperature of 235 °C
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX

### Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1 - 3, 8 - 10, 13 - 18, 20, 22 - 28, 30 - 32	N/C	No Connection. These pins may be connected to RF/DC ground. Performance will not be affected.	
4	RFOUT/4	Divide-by-4 output. DC block required.	5V RFOUT/4
6	Vcc (Dig)	Supply voltage for prescaler. If prescaler is not required, this pin may be left open to conserve approximately 65 mA of current.	Vcc(Dig)  ———————————————————————————————————





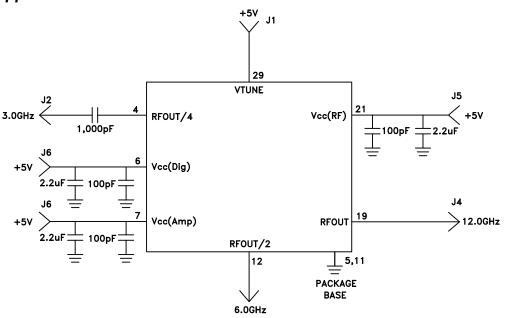
# MMIC VCO w/ HALF FREQUENCY OUTPUT & DIVIDE-BY-4, 11.5 - 12.8 GHz

### **Pin Descriptions**

Pin Number	Function	Description	Interface Schematic
7	Vcc (Amp)	Supply voltage, for RFOUT/2 output. If RFOUT/2 is not required, this pin may be left open to conserve approximately 30 mA of current.	Vcc(Amp)  14pF
12	RFOUT/2	Half frequency output (AC coupled).	PFOUT/2
19	RF OUT	RF output (AC coupled).	RFOUT
21	Vcc (RF)	Supply Voltage, +5V	Vcc(RF)
29	VTUNE	Control voltage and modulation input. Modulation bandwidth dependent on drive source impedance. See "Determining the FM Bandwidth of a Wideband Varactor Tuned VCO" application note.	3nH VTUNE ○
5, 11, Paddle	GND	Package bottom has an exposed metal paddle that must be connected to RF/DC ground.	→ GND =

v03.1210

### **Typical Application Circuit**

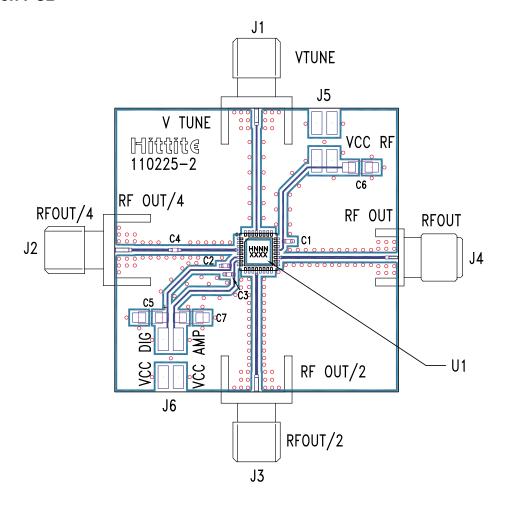






# MMIC VCO w/ HALF FREQUENCY OUTPUT & DIVIDE-BY-4, 11.5 - 12.8 GHz

#### **Evaluation PCB**



#### List of Materials for Evaluation PCB 110227 [1]

Item	Description
J1 - J4	PCB Mount SMA RF Connector
J5 - J6	2 mm DC Header
C1 - C3	100 pF Capacitor, 0402 Pkg.
C4	1,000 pF Capacitor, 0402 Pkg.
C5 - C7	2.2 µF Tantalum Capacitor
U1	HMC583LP5 / HMC583LP5E VCO
PCB [2]	110225 Eval Board

<sup>[1]</sup> Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and backside ground paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.